

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

SATO et al.

Group Art Unit: Unknown

Application No.: New U.S. Patent Application

Examiner: Unknown

Filed: November 30, 2001

Attorney Dkt. No.: 108384-00034

For: RESIN COMPOUND FOR FABRICATING INTERLAYER DIELECTRIC OF
PRINTED WIRING BOARD, RESIN SHEET AND RESIN APPLIED-COPPER FOIL
FOR FORMING INSULATION LAYER USING THE RESIN COMPOUND, AND
COPPER-CLAD LAMINATE USING THEM

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

November 30, 2001

Sir:

Prior to initial examination of the application, please amend the above-identified
application as follows:

IN THE CLAIMS:

Please amend claims 4, 5, 6, 7, 9 and 10 as follows:

4. (Amended) The resin compound used for fabricating the interlayer dielectric of
the printed wiring board as set forth in Claim 2, wherein the polymers having
crosslinkable functional groups within a molecule are any one or more of polyether
sulfone resin having a hydroxyl group at a terminal, polyvinyl acetal resin having
repeated hydroxyl groups within a molecule, and phenoxy resin.